



PCN Number:	20240221013.1			PCN Date:	February 22, 2024												
Title:	Qualification of TIPI as an additional Assembly site for select devices																
Customer Contact:	Change Management team		Dept:	Quality Services													
Proposed 1st Ship Date:	May 22, 2024		Sample Requests accepted until:	\$CRF_SamplesAcceptedUntil\$*													
March 23, 2024 will not be supported.																	
Change Type:																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material												
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for set of devices listed below. Construction differences are as follows:																	
<table border="1"> <thead> <tr> <th></th> <th>AP3</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td>Wire type/diam</td> <td>0.8mil Au</td> <td>0.8mil Cu</td> </tr> <tr> <td>Mount Compound</td> <td>101375377</td> <td>4205412</td> </tr> <tr> <td>Mold Compound</td> <td>101342201</td> <td>4206745</td> </tr> </tbody> </table>							AP3	TIPI	Wire type/diam	0.8mil Au	0.8mil Cu	Mount Compound	101375377	4205412	Mold Compound	101342201	4206745
	AP3	TIPI															
Wire type/diam	0.8mil Au	0.8mil Cu															
Mount Compound	101375377	4205412															
Mold Compound	101342201	4206745															
Reason for Change:																	
Supply continuity																	
1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Impact on Environmental Ratings																	
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																	
RoHS		REACH		Green Status													
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change													
Changes to product identification resulting from this PCN:																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>AMKOR P3</td> <td>AP3</td> <td>PHL</td> <td>Binan</td> </tr> <tr> <td>TI Philippines</td> <td>PHI</td> <td>PHL</td> <td>Baguio City</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	AMKOR P3	AP3	PHL	Binan	TI Philippines	PHI	PHL	Baguio City
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City														
AMKOR P3	AP3	PHL	Binan														
TI Philippines	PHI	PHL	Baguio City														
Sample product shipping label (not actual product label)																	

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS
Product Affected:		
AFE5828ZAV		AFE58JD28ZAV

Qualification Report

Approve Date 23-January-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AFE5828ZAV
UHAIST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0
FTY	E6	Final Test Yield	-	-	3/3/0

QBS: Qual By Similarity

Qual Device AFE5828ZAV is qualified at MSL3 260C

Qual Device AFE5828ZAV is qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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